

REMARKS

Claims 1-8 are pending in the application.

Claims 4-8 are withdrawn from consideration.

Claim 1 is rejected under 35 U.S.C. §102 as being anticipated by Tetsuo Mochizuki et al., (JP409181445A), hereafter Tetsuo.

Claims 2 and 3 are rejected under 35 U.S.C. §103 as being unpatentable over Tetsuo in view of Hideo Takada (Japanese publication 07-263871).

Claim 2 is canceled and claim 1 is amended to more clearly define the invention over the prior art.

Tetsuo teaches a block of printed boards having two conductive layers on one side of the substrate 11. Tetsuo does not specifically teach a form of interconnects including electrically-floating conductive layers. In Tetsuo, Fig. 2 shows the block of printed board having 16 printed circuit boards.

In Tetsuo, first interconnecting patterning area 12 and first dummy pattern 13 are formed on the dielectric substrate 11. Then the dielectric layer 14 is disposed on the first interconnect patterning area 12 and first dummy pattern 13. Second interconnect patterning area 17 and second dummy pattern 15 are formed on the dielectric layer 14. Fig. 1 shows a cross-sectional view of a plan view of the printed wiring board in Fig. 2. The dummy pattern 15 is lost when each of the printed circuit boards 18 is cut out separately as a final product.

Tetsuo simply teaches a block of printed boards having two conductive layers on one side. Tetsuo does not explicitly teach a single board having electrically-floating patterns and the interconnect patterning areas 12, 17 corresponding to the present invention.

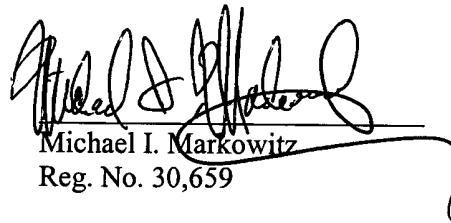
Figs. 4-7 in the present invention clearly shows a discrete single board.

According to the present invention, the single printed boards having the top/bottom interconnect layer patterns 17, 18 include the electrically-floating conductive layers 20, 21, (page 7, lines 6-23 in the present specification). According to the present invention, the top/bottom electrically-floating conductive layers 20, 21 cover remaining areas where wiring is not necessary, (page 9, lines 4-19 in the present specification). The metallic film covers substantial area of the board so that penetration of water or a crack can be prevented, (page 10, lines 16-25 in the present specification).

In view of the remarks set forth above claims 1 and 3 are in condition for allowance. However, if for any reason the Examiner would not consider claims 1 and 3 as allowable, the Examiner is respectfully requested to telephone the undersigned attorney at the number listed below prior to issuing a further action.

Any fee due with this paper may be changed to Deposit Account 50-1290.

Respectfully submitted,



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